



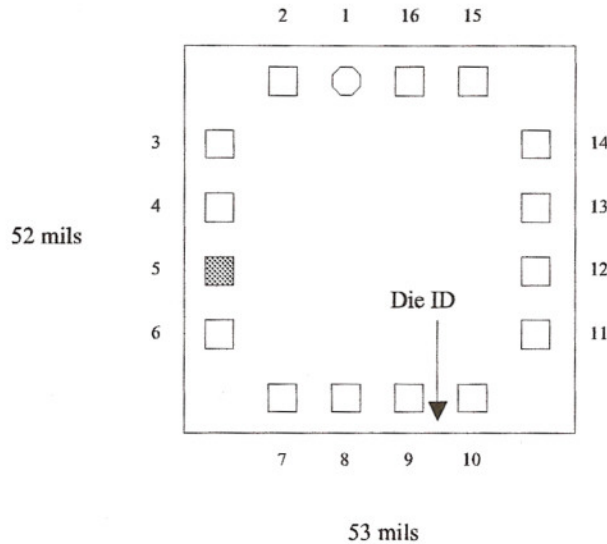
Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

PAD FUNCTION

- 1 COLLECTOR Q1
- 2 COLLECTOR Q2
- 3 EMITTER Q2
- 4 BASE Q2
- 5 NC
- 6 COLLECTOR Q3
- 7 EMITTER Q3
- 8 BASE Q3
- 9 BASE Q4
- 10 EMITTER Q4
- 11 COLLECTOR Q4
- 12 COLLECTOR Q5
- 13 EMITTER Q5
- 14 BASE Q5
- 15 BASE Q1
- 16 EMITTER Q1

NC = NO CONNECT



NOTES:
 Chip back must be connected to V-
 For orientation bond pad 1 metal is circular

The information given is believed to be correct at the time of issue.
 Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.
 Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Pad positions shall obey the following rules:

1. Pad functions shall not change sequence and shall agree with the above definitions.
2. No pad function shall move by more than 1mm from the position shown.
3. No pad function shall move from a corner, and another move into that corner, even if the above constraints are met.

Note: 1 mil = 0.001inch

<p><u>APPROVED</u></p> <p>D Markham</p> <p>DATE: 16/03/01</p>	<p>HFA3127Y</p> <p>HARRIS</p>	<p><u>DIE INFORMATION</u></p> <p>DIMENSIONS (Mils): 53 x 52 x 14 BOND PADS (Mils): 4 x 4 MASK. REF: A GEOMETRY: BACK POTENTIAL: V- (SEE NOTE)</p>
<p><u>SERIAL NUMBER</u></p> <p>003936</p>		<p><u>METALLISATION</u></p> <p>TOP: Al BACK: Au or Si</p>